



# GT150HF120T1NH

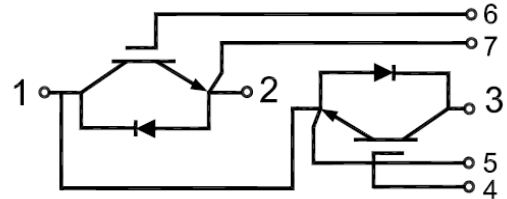
## IGBT Module

Preliminary Data

### Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10 $\mu$ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested(2xI<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

### Circuit Diagram



### Applications:

- Welding
- HEV Inverter
- Industrial Motor Drives
- UPS

### IGBT, Brake-Chopper Maximum Rated Values of IGBT

V <sub>CEs</sub>	Collector-Emitter Blocking Voltage	T <sub>J</sub> =25°C	1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		±20	V
I <sub>c</sub>	Continuous Collector Current	T <sub>C</sub> =100°C	150	A
		T <sub>C</sub> =25°C	300	A
I <sub>CM</sub>	Repetitive Peak Collector Current	tp=1ms	300	A
t <sub>sc</sub>	Short Circuit Withstand Time		>10	μs
P <sub>D</sub>	Maximum Power Dissipation per IGBT	T <sub>C</sub> =25°C T <sub>Jmax</sub> =175°C	987	W



## Electrical Characteristics of IGBT

### Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units.	
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=6mA, V_{CE}=V_{GE}, T_J=25^\circ C$	5.0	6.2	6.5	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=150A, V_{GE}=15V$	$T_J=25^\circ C$		2.30	2.60	V
			$T_J=125^\circ C$		3.30		V
			$T_J=150^\circ C$		3.60		V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0V, V_{CE}=V_{CES}, T_J=25^\circ C$			1	mA	
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20V, V_{CE}=0V, T_J=25^\circ C$			200	nA	
$C_{ies}$	Input Capacitance	$V_{CE}=25V, V_{GE}=0V, f=100kHz, T_J=25^\circ C$		12.96		nF	
$C_{oes}$	Out Capacitance			0.87		nF	
$C_{res}$	Reverse Transfer Capacitance			0.39		nF	

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V, I_C=150A, R_{Gon}=10\Omega, V_{GE}=\pm 15V, \text{Inductive Load}$	$T_J=25^\circ C$		334		ns
			$T_J=125^\circ C$		336		
			$T_J=150^\circ C$		334		
$t_r$	Rise Time		$T_J=25^\circ C$		107		ns
			$T_J=125^\circ C$		117		
			$T_J=150^\circ C$		118		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ C$		175		ns
			$T_J=125^\circ C$		176		
			$T_J=150^\circ C$		176		
$t_f$	Fall Time	$T_J=25^\circ C$		133		ns	
		$T_J=125^\circ C$		147			
		$T_J=150^\circ C$		145			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=600V, I_C=150A, R_{Gon}=10\Omega, V_{GE}=\pm 15V, di/dt=1085A/\mu s (T_J=150^\circ C) \text{ Inductive Load}$	$T_J=25^\circ C$		12.3		mJ
		$T_J=125^\circ C$		19.8			
		$T_J=150^\circ C$		21.5			



E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =600V, I <sub>C</sub> =150A, R <sub>Goff</sub> =10Ω, V <sub>GE</sub> =±15V, du/dt=8304V/μs (T <sub>J</sub> =150°C) Inductive Load	T <sub>J</sub> =25°C	6.2	mJ
			T <sub>J</sub> =125°C	8.2	
			T <sub>J</sub> =150°C	8.4	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =+15V...-15V	T <sub>J</sub> =25°C	0.59	μC
R <sub>g internal</sub>	Internal Gate Resistance		T <sub>J</sub> =25°C	1	Ω
RBSOA	I <sub>C</sub> =300A, V <sub>CC</sub> =1050V, V <sub>p</sub> =1200V, R <sub>G</sub> =10Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C			Trapezoid	
SCSOA	V <sub>CC</sub> =600V, R <sub>Gon</sub> =10Ω, R <sub>Goff</sub> =10Ω, V <sub>GE</sub> =+/-15V, T <sub>J</sub> =125°C			450	A
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-To-Case (per IGBT)			0.152	°C/W

### Maximum Rated Values of Diode

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	T <sub>J</sub> =25°C	1200	V
I <sub>F</sub>	Diode Continuous Forward Current		150	A
I <sub>FM</sub>	Peak FWD Current Repetitive	tp=1ms	300	A

### Electrical Characteristics of Diode

Symbol	Description	Conditions	Min.	Typ.	Max.	Units.
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =150A	T <sub>J</sub> =25°C	2.60		V
			T <sub>J</sub> =125°C	2.70		
			T <sub>J</sub> =150°C	2.70		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =150A, -diF/dt=980A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	130		ns
			T <sub>J</sub> =125°C	260		
			T <sub>J</sub> =150°C	385		
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =150A, -diF/dt=980A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	53		A
			T <sub>J</sub> =125°C	75		
			T <sub>J</sub> =150°C	85		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =150A, -diF/dt=980A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	5.02		μC
			T <sub>J</sub> =125°C	10.84		
			T <sub>J</sub> =150°C	11.58		



E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =150A, -diF/dt=980A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	2.21	mJ
			T <sub>J</sub> =125°C	4.75	
			T <sub>J</sub> =150°C	5.81	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-To-Case (per Diode)			0.332	°C/W

## Module

Symbol	Description		Min.	Typ.	Max.	Units.
V <sub>iso</sub>	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 30s	4500			V
T <sub>J</sub>	Maximum Junction Temperature				175	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range		-55		+150	°C
T <sub>stg</sub>	Storage Temperature		-55		+150	°C
CTI	Comparative Tracking Index		200			
R <sub>θCS</sub>	Case-To-Sink Thermally (Conductive Grease Applied)				0.07	°C/W
T	Power Terminals Screw:M5		3.0		5.0	N·m
T	Mounting Screw:M6		4.0		6.0	N·m
G	Weight			150		g

## Ordering Information Table

Device code	G	T	150	HF	120	T1N	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Field Stop Trench Gate IGBT
- ③ - Rated Current (150=150A)
- ④ - Circuit Configuration: HF (Half Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

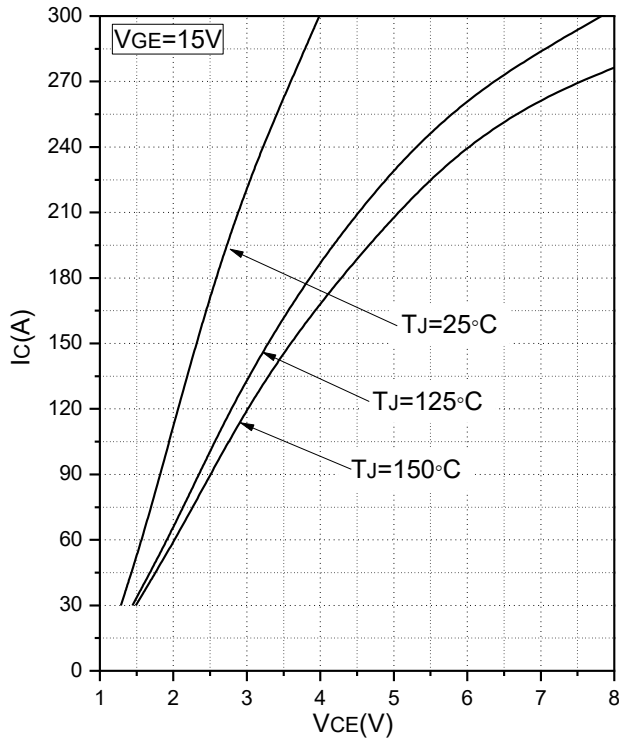


Fig.1 Typical Saturation Voltage Characteristics

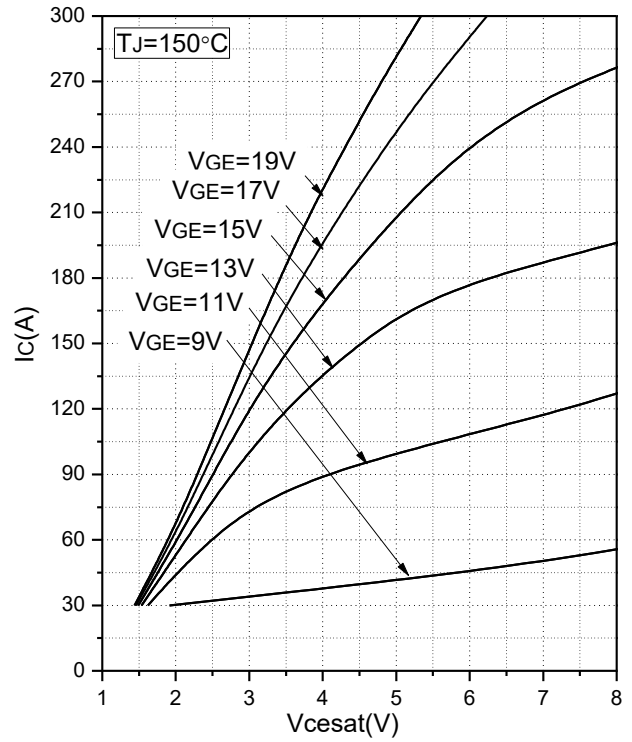


Fig.2 Typical Output Characteristics

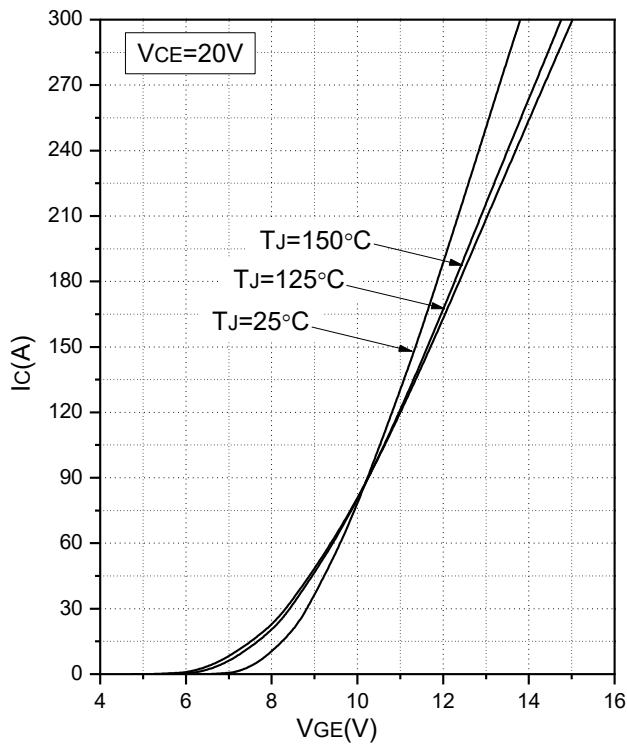


Fig.3 Transfer Characteristic

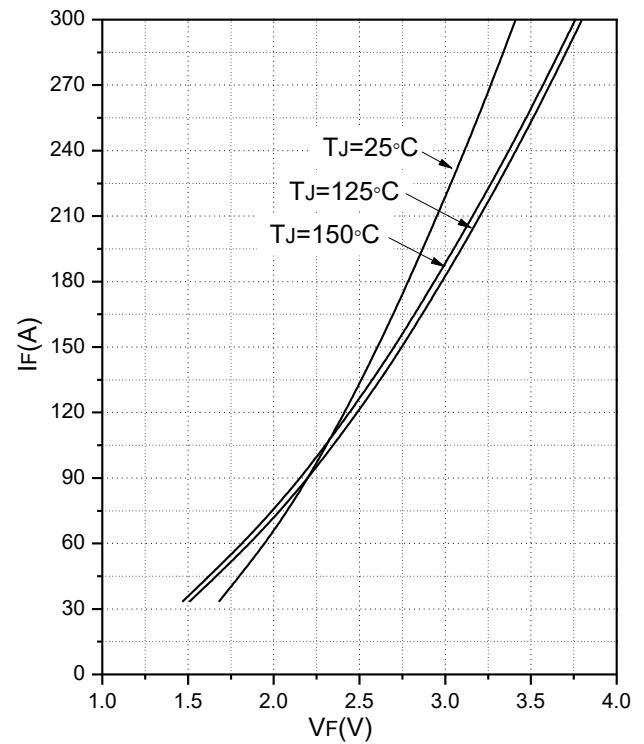


Fig.4 Forward Characteristics of Diode

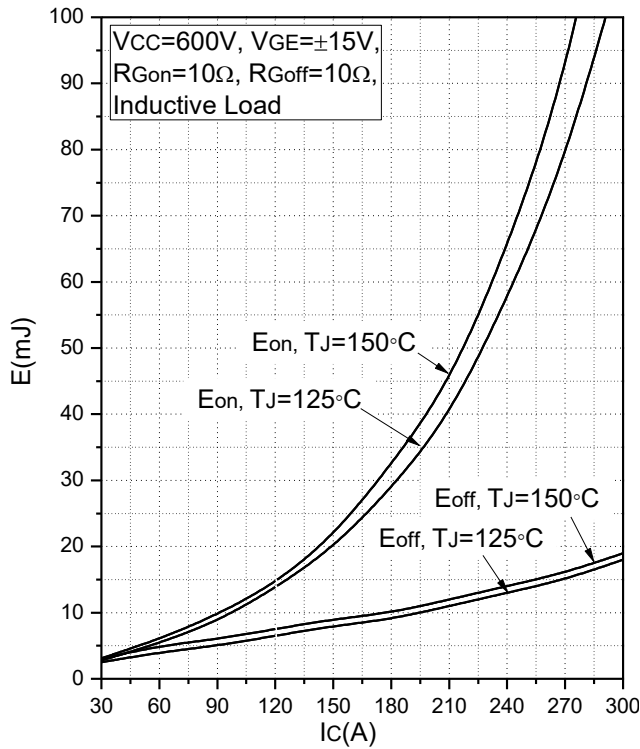


Fig.5 Typical Switching Loss vs. Collector Current

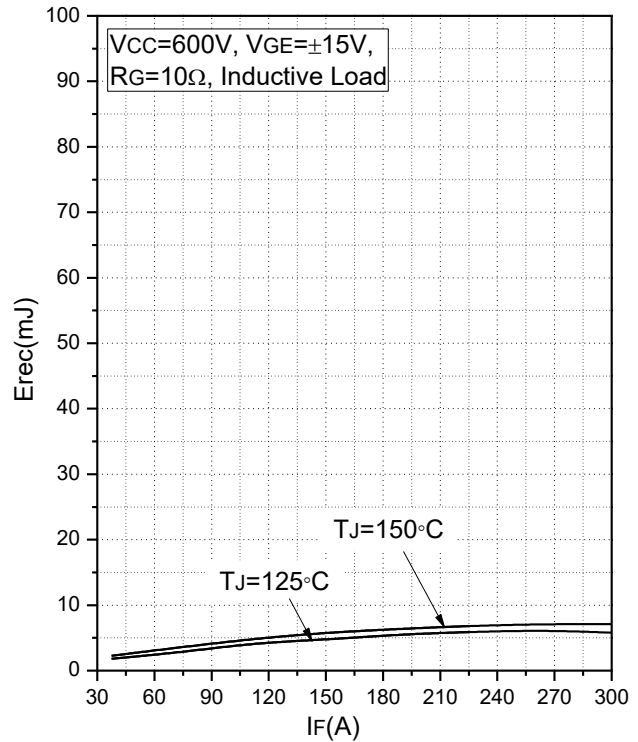


Fig.6 Typical Switching Loss vs. Forward Current

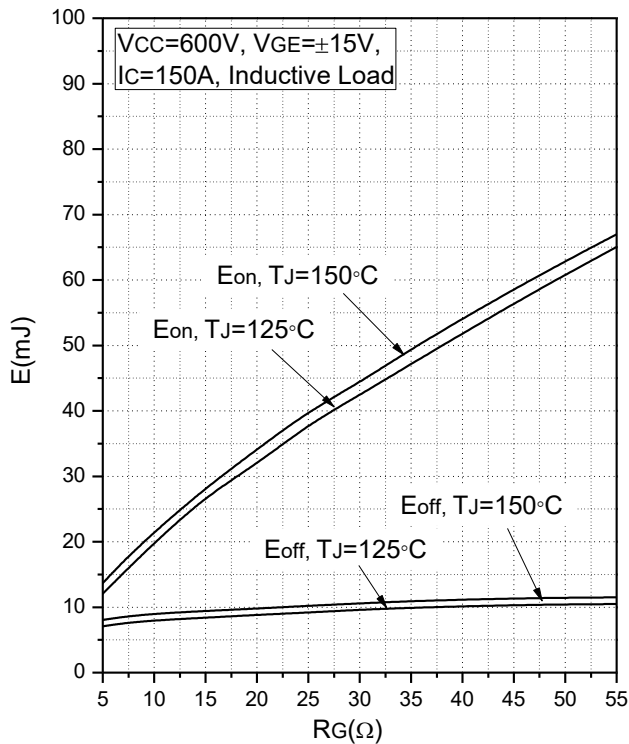


Fig.7 Typical Switching Loss vs. Gate Resistance

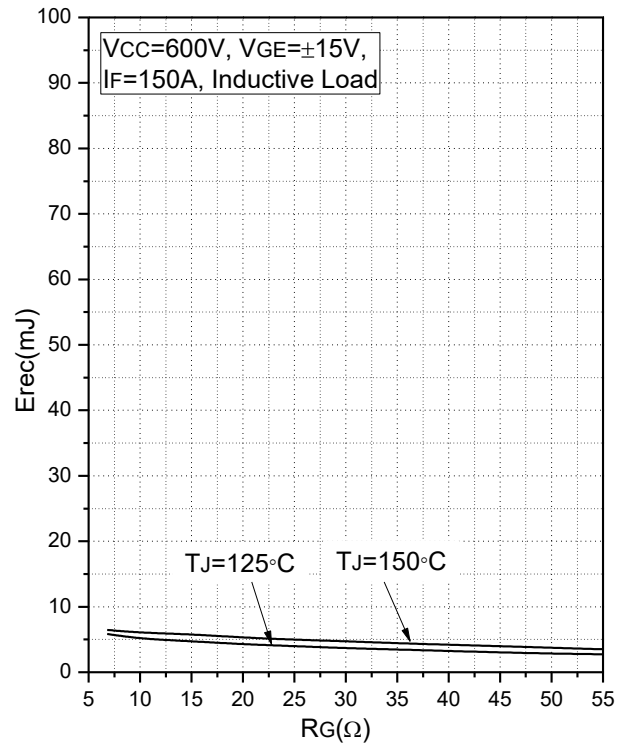


Fig.8 Typical Switching Loss vs. Gate Resistance

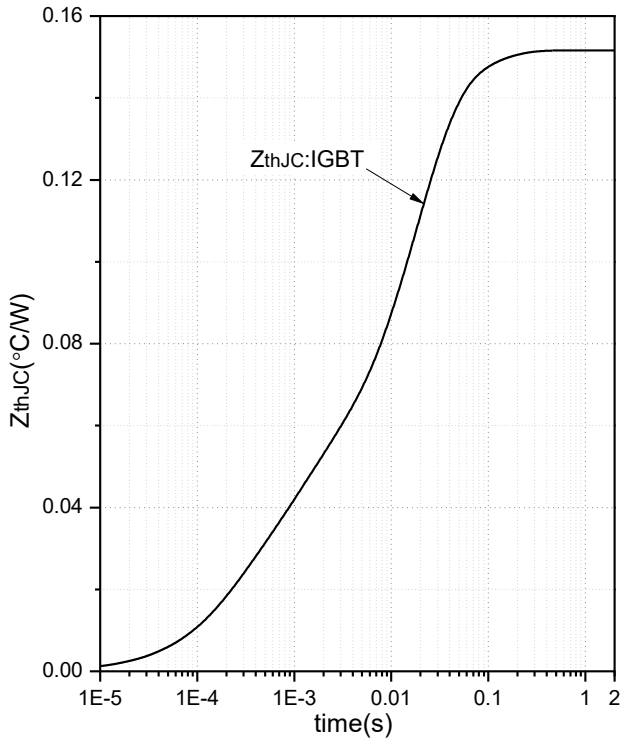


Fig.9 Transient Thermal Impedance (IGBT)

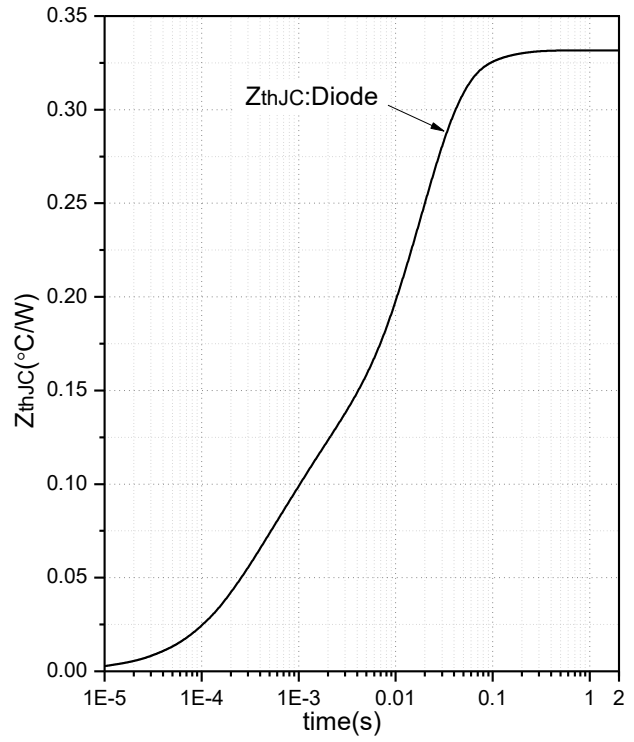


Fig.10 Transient Thermal Impedance (Diode)

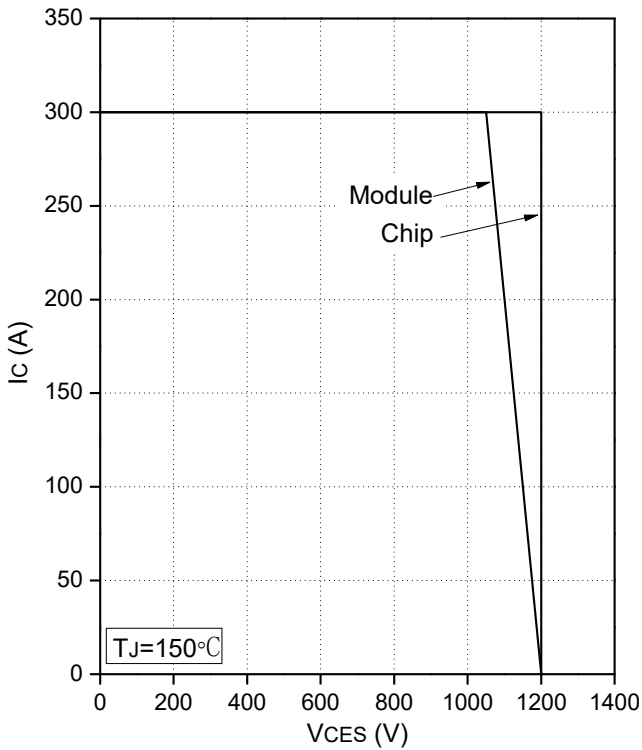
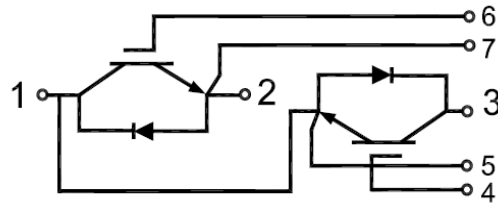


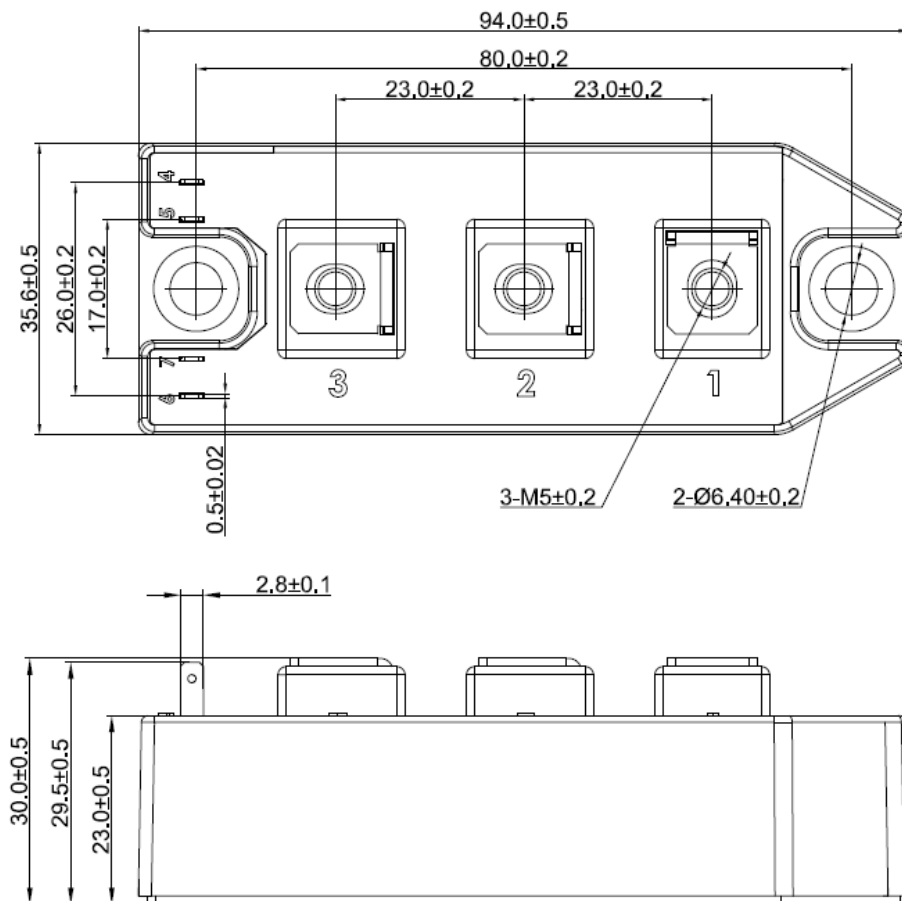
Fig.11 Reverse Bias Safe Operation Area (RBSOA)



## Internal Circuit



## Package Outline (Unit: mm):







Date	Revision	Notes
08/30/2023	01	Initial release

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